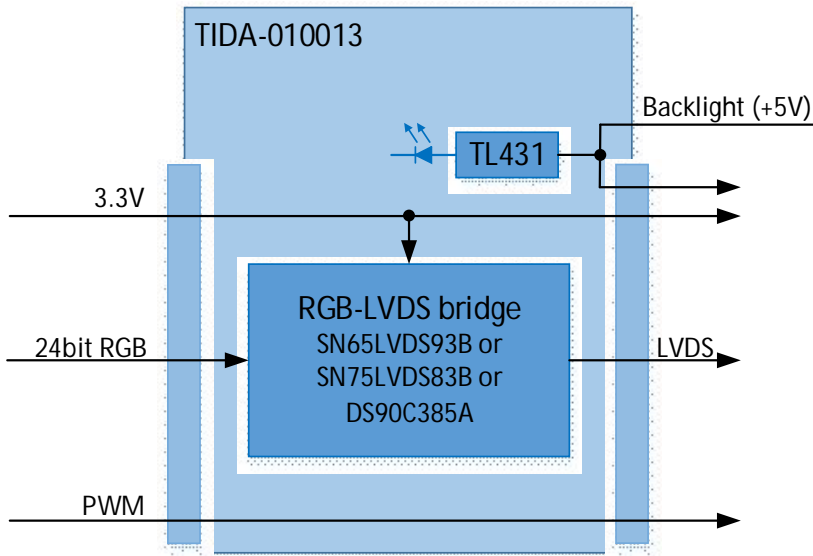


Revision History

Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A

Block Diagram



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Orderable: EVM, orderable	Designed for: Public Release	Mod. Date: 6/21/2018
TID #: N/A	Project Title: RGB LVDS Video Bridge	
Number: TIDA-010013 Rev: E2	Sheet Title:	
SVN Rev. Version control disabled	Assembly Variant: [No Variations]	Sheet: 1 of 3
Drawn By:	File: TIDA-010013_CoverSheet_SchDoc	Size: B
Engineer: Lars Lotzenburger	Contact: http://www.ti.com/support	http://www.ti.com

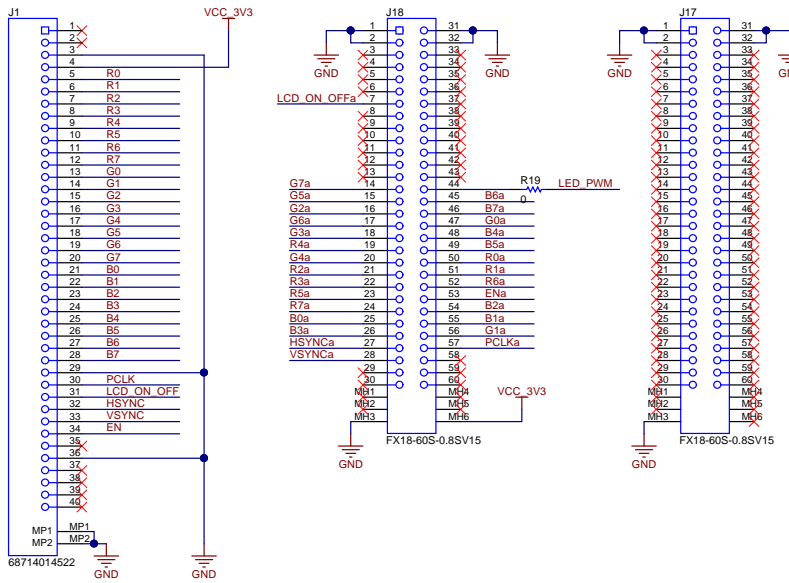


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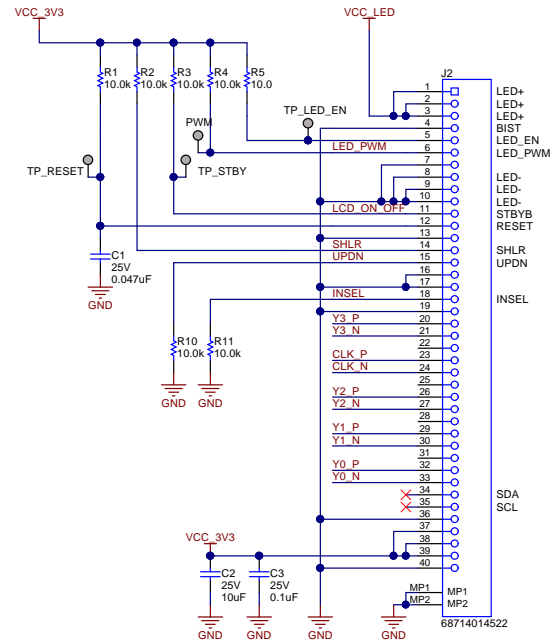
Video Input (24b RGB)

AM335x Starter Kit

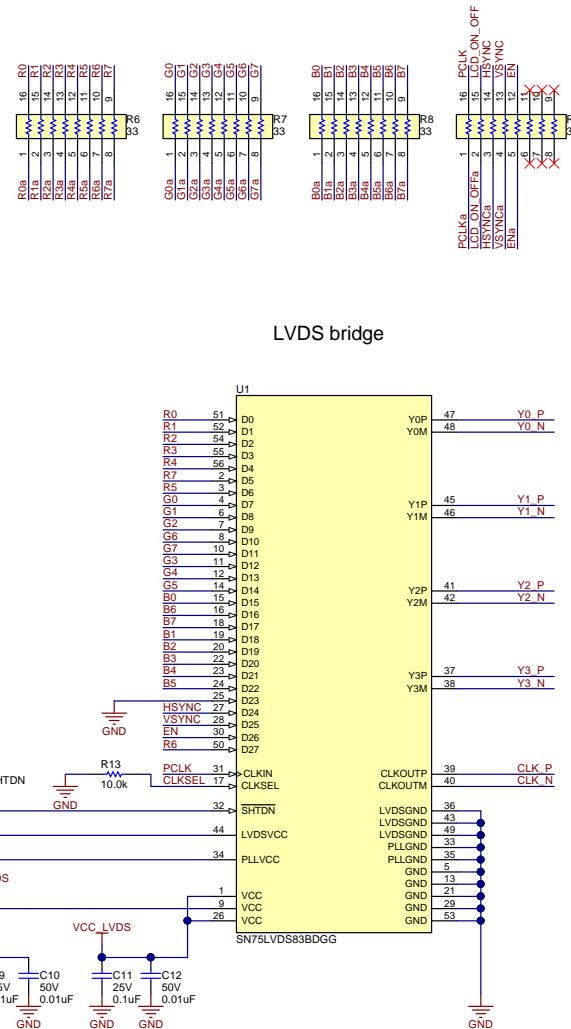
AM572X Evaluation Module (processor card)



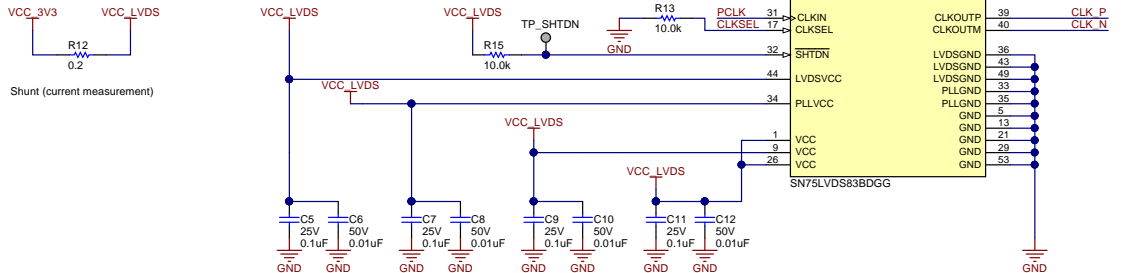
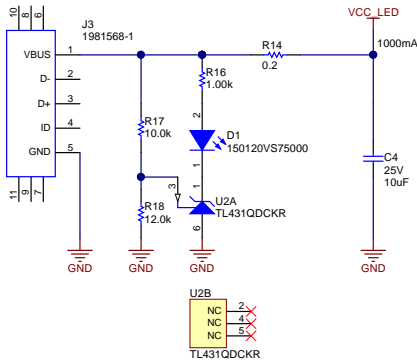
Video Output (LVDS)



LVDS bridge



External Power for LED backlight



When using TP_PWM_IN make sure this circuit generates 99% duty cycle

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TID #: N/A	Project Title: RGB LVDS Video Bridge	
Number: TIDA-010013 Rev: E2	Sheet Title:	
SVN Rev. Version control disabled	Assembly Variant: [No Variations]	Sheet: 2 of 3
Drawn By:	File: TIDA-010013_Schematic_SchDoc	Size: B
Engineer: Lars Lotzenburger	Contact: http://www.ti.com/support	

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PCB Number: TIDA-010013
PCB Rev: E2

Logo1
PCB
LOGO
WEEE logo

PCB
LOGO

Variant/Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
This Assembly Note will show in the PcbDoc and associated outputs

ZZ3
Assembly Note
This Assembly Note will show in the PcbDoc and associated outputs

ZZ4
Assembly Note
This Assembly Note will show in the PcbDoc and associated outputs

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Orderable: EVM, orderable	Designed for: Public Release	Mod. Date: 6/21/2018
TID #: N/A	Project Title: RGB LVDS Video Bridge	
Number: TIDA-010013 Rev: E2	Sheet Title:	
SVN Rev. Version control disabled	Assembly Variant: [No Variations]	Sheet: 3 of 3
Drawn By:	File: TIDA-010013 EVM Hardware_SchDoc	Size: B
Engineer: Lars Lotzenburger	Contact: http://www.ti.com/support	



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